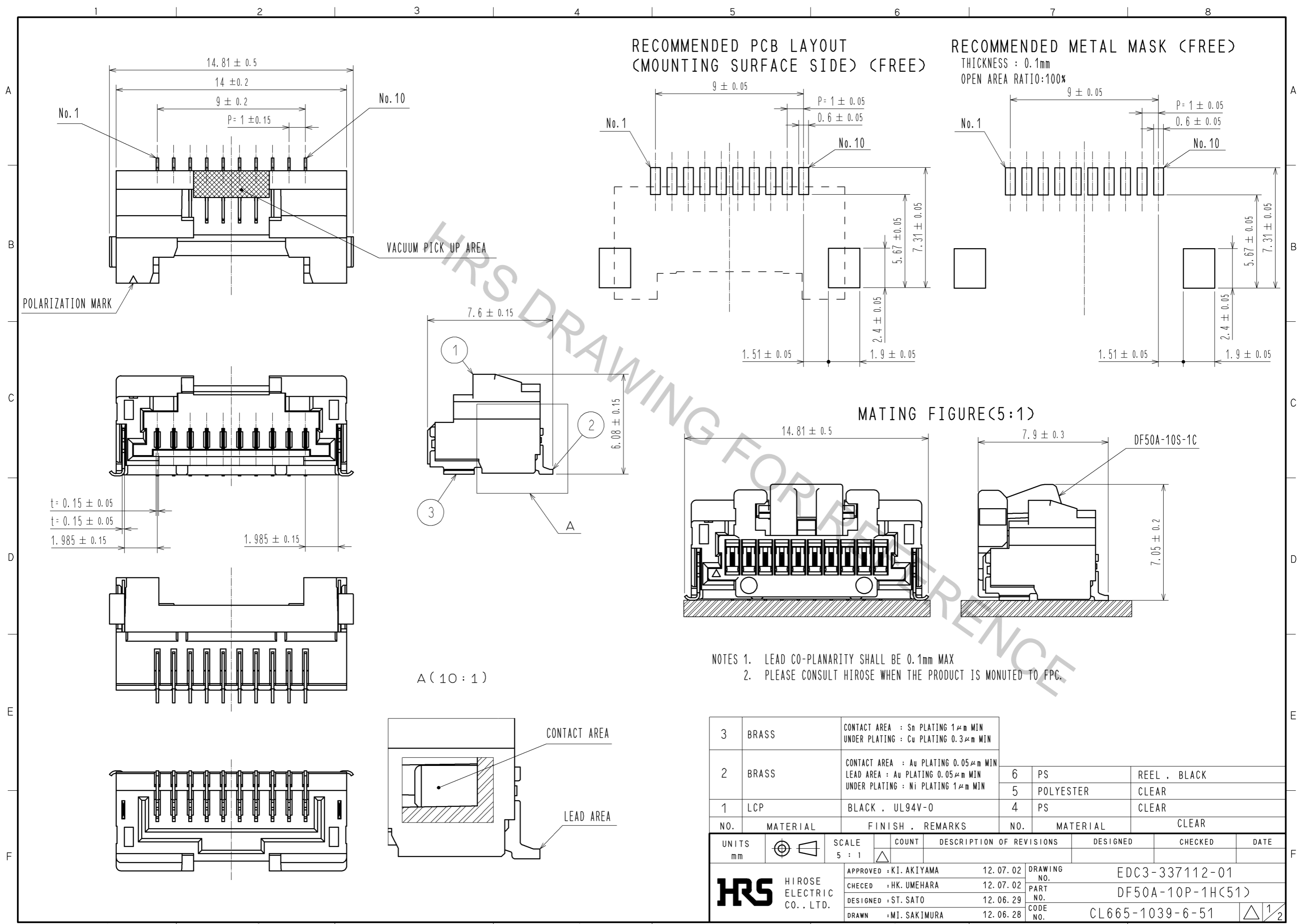


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RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)

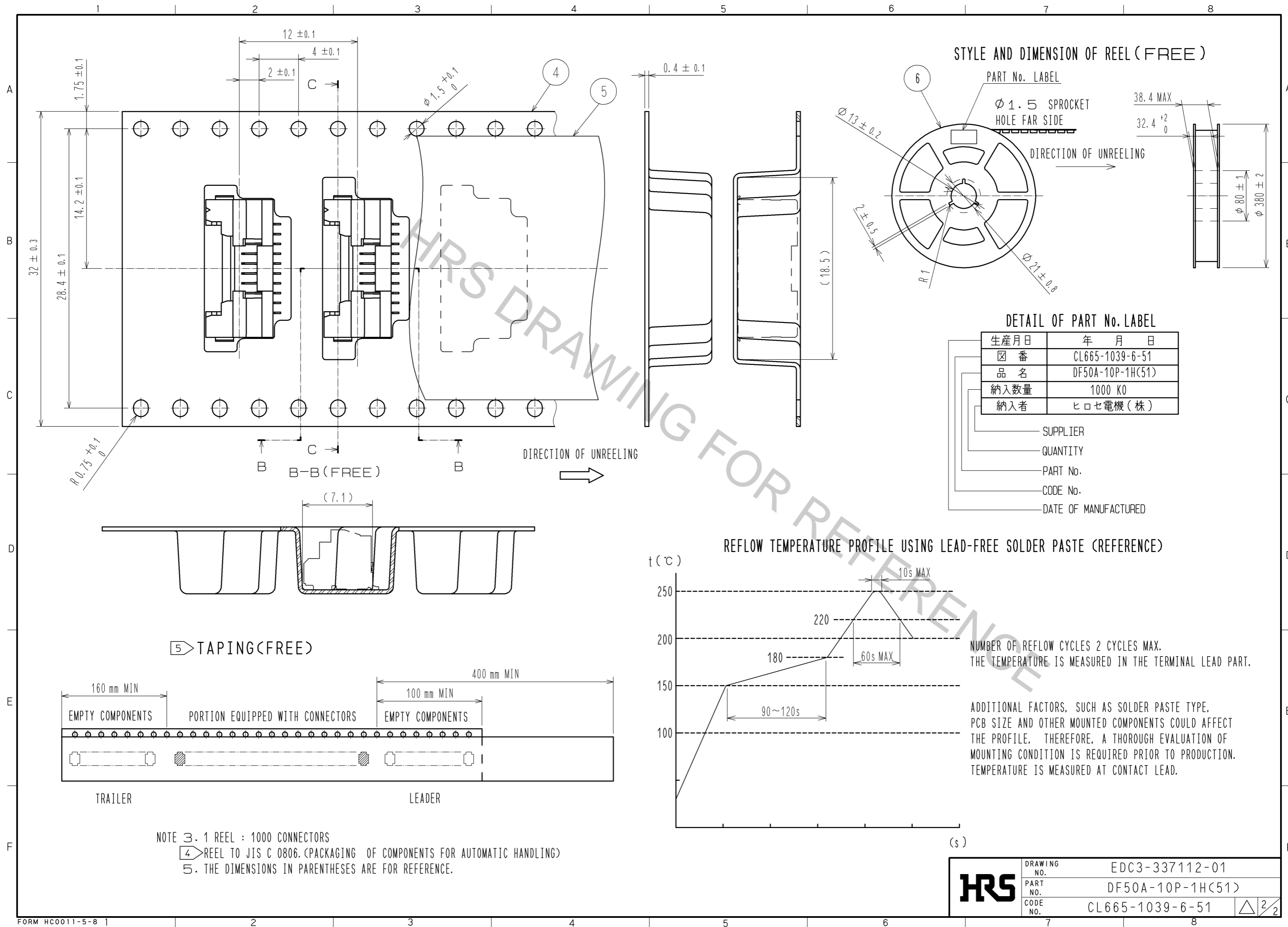
RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm
OPEN AREA RATIO:100%

MATING FIGURE(5:1)

- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
2. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

3	BRASS	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Cu PLATING 0.3μm MIN			
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	6	PS	REEL , BLACK
1	LCP	BLACK , UL94V-0	5	POLYESTER	CLEAR
			4	PS	CLEAR
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	CLEAR

UNITS mm		SCALE 5 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HRS	HIROSE ELECTRIC CO., LTD.	APPROVED : KI. AKIYAMA 12.07.02			DRAWING NO. EDC3-337112-01		
		CHECED : HK. UMEHARA 12.07.02			PART NO. DF50A-10P-1H(51)		
		DESIGNED : ST. SATO 12.06.29			CODE NO. CL665-1039-6-51		
		DRAWN : MI. SAKIMURA 12.06.28					1/2



STYLE AND DIMENSION OF REEL (FREE)

PART No. LABEL

φ 1.5 SPROCKET HOLE FAR SIDE

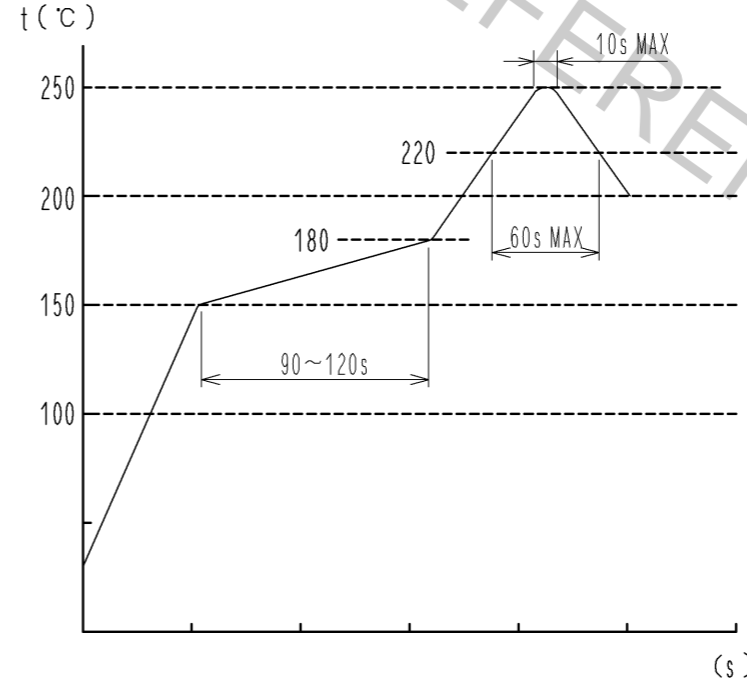
DIRECTION OF UNREELING

DETAIL OF PART No. LABEL

生産月日	年月日
図番	CL665-1039-6-51
品名	DF50A-10P-1H(51)
納入数量	1000 KO
納入者	ヒロセ電機(株)

- SUPPLIER
- QUANTITY
- PART No.
- CODE No.
- DATE OF MANUFACTURED

REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX.
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.

ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

- NOTE 3. 1 REEL : 1000 CONNECTORS
- ④ REEL TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
 - ⑤ THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

HRS	DRAWING NO.	EDC3-337112-01
	PART NO.	DF50A-10P-1H(51)
	CODE NO.	CL665-1039-6-51
		△ 2/2